

Title (en)  
MANUFACTURING PROCESS FOR INTEGRATED PIEZOELECTRIC COMPONENTS

Title (de)  
FERTIGUNGSPROZESS FÜR INTEGRIERTE PIEZO-BAUELEMENTE

Title (fr)  
PROCEDE DE FABRICATION DE COMPOSANTS PIEZOELECTRIQUES INTEGRES

Publication  
**EP 1987337 A1 20081105 (DE)**

Application  
**EP 07703486 A 20070216**

Priority  
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• DE 102006008584 A 20060224

Abstract (en)  
[origin: US2007202628A1] A method is provided for the production of integrated microelectromechanical elements, in which first a silicon layer is formed on an insulation layer, then a piezoresistive layer on or in the silicon layer, and then at least one etch opening for etching at least one cavity substantially within the silicon layer. The shape of the cavity in the silicon layer is predefined by arrangement of additional vertical and horizontal etch stop layers, and the etching process is readily reproducible. The method is suitable for being integrated into standard fabrication processes particularly with circuit components needed for signal conditioning and signal processing.

IPC 8 full level  
**G01L 9/00** (2006.01); **H10N 39/00** (2023.01); **B81B 3/00** (2006.01)

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**B81C 1/00246** (2013.01 - EP US); **G01L 9/0042** (2013.01 - EP US); **G01L 9/0054** (2013.01 - EP US); **B81B 2201/0264** (2013.01 - EP US); **B81C 2203/0742** (2013.01 - EP US)

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